



IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: ZHU, et al. Conf.: 2830
Appl. No.: 09/842,768 Group: 2817
Filed: April 27, 2001 Examiner: Stephen JONES
For: HIGH-FREQUENCY MULTILAYER CIRCUIT
SUBSTRATE

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PATENT
0020-4855P
1/16/03
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REPLY UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents
Washington, DC 20231

January 6, 2003

Sir:

In reply to the Examiner's Office Action dated September 4, 2002, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

IN THE SPECIFICATION:

Please replace the paragraph beginning on page 6, line 15, with the following rewritten paragraph:

--Taking high-frequency characteristics of a via hole into consideration, the present inventor discovered a method for eliminating signal wave reflection in the via hole connecting portion and a transmission loss due to the reflection by regarding the via hole as a circuit component having a characteristic impedance different from that of a signal transmission line and by providing an adjustable